

# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>R</sub> wm V <sub>R</sub>	400	V
Average Rectified Output Current	lo	1	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	А

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 6)	$R_{ heta JC}$	63	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	118	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R <sub>0JA</sub>	95	°C/W
Operating and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to +150	°C

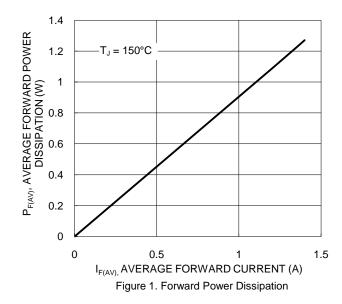
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

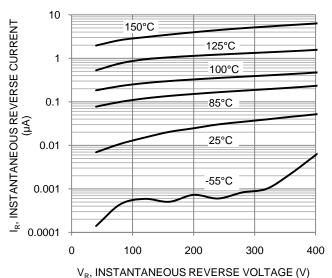
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	400		_	V	$I_R = 10\mu A$
Forward Voltage	V <sub>F</sub>	_	1.1 0.9	1.25 —	V	I <sub>F</sub> = 1A, T <sub>J</sub> = +25°C I <sub>F</sub> = 1A, T <sub>J</sub> = +125°C
Reverse Leakage Current (Note 7)	I <sub>R</sub>	_	0.1 2	1 10	μA	$V_R = 400V, T_J = +25$ °C $V_R = 400V, T_J = +100$ °C
Reverse Recovery Time	t <sub>RR</sub>	_	28	35	ns	$I_F = 0.5A$ , $I_R = 1.0A$ , $I_{RR} = 0.25A$
Typical Total Capacitance	$C_T$	_	9	_	pF	$V_R = 4V$ , $f=1MHz$

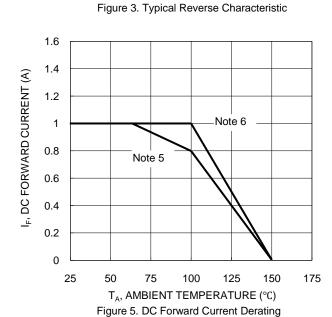
Notes:

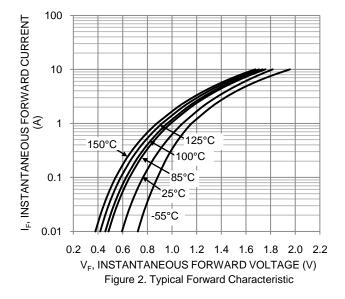
- 5. Device mounted on FR-4 substrate, 1"\*1", 2oz, single-sided, PC boards with 0.1"\*0.15" copper pad. 6. Device mounted on FR-4 substrate, 0.4"\*0.5", 2oz, single-sided, PC boards with 0.2"\*0.25" copper pad.
- 7. Short duration pulse test used to minimize self-heating effect.











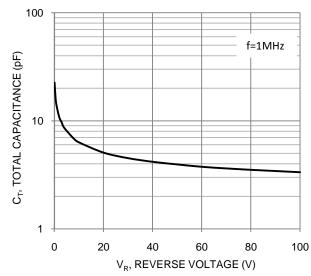


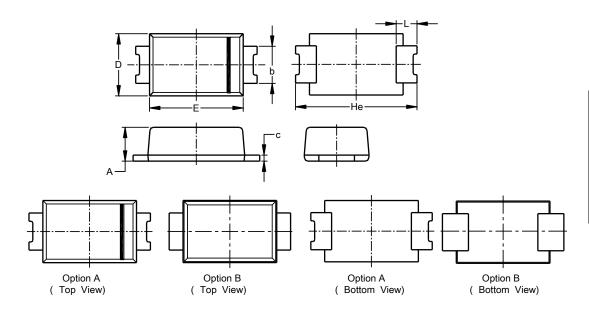
Figure 4. Total Capacitance vs. Reverse Voltage



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOD123F (Standard)

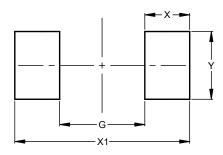


SOD123F (Standard)			
Dim	Min	Max	Тур
Α	0.81	1.15	-
b	0.80	1.35	-
С	0.05	0.30	-
ם	1.70	1.90	1.80
Е	2.60	2.80	2.70
He	3.30	3.70	3.50
J	0.35	0.85	1
All Dimensions in mm			

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOD123F (Standard)



Dimensions	Value (in mm)
G	1.90
Х	1.00
X1	3.90
Y	1.50



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